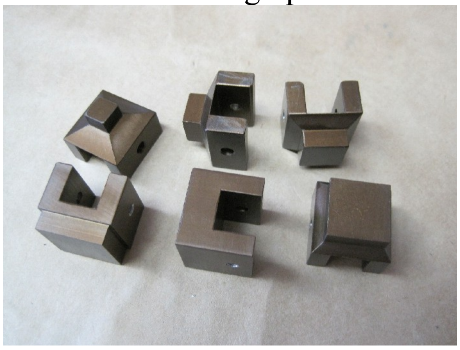
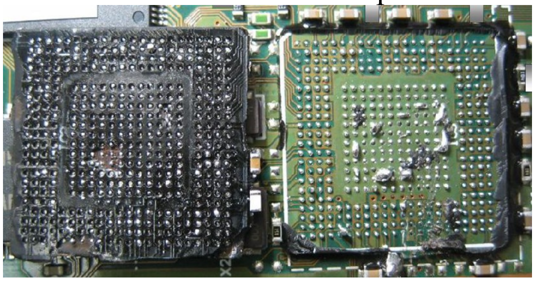
BGA Remover for Smartphone, Automotive navigation system and Tablet PC.

Do you have a hard time by the removal of BGA with underfill ?

Heating tip



BGA removal example



BGA Remover Model:BR-515

BR-515 is an exclusive device removing BGA from PCB of a Smartphone, Aoutmotive navigation system and Tablet PCs. This device removes BGA which applied underfill material easily in 20-80 seconds. And positioning of PCB is very simple, too. Accordingly 1/3-1/10 can shorten work time than the BGA removal by Rework stations. And repair yield improves very much.

Features

- BR-515 removes BGA with underfill from PCB in 20-80 seconds.
- This device is overheated with a heating tip directly from the BGA upper part.
- This device fits strongest epoxy underfill material.
- This device removes BGA from PCB before underfill material does curing by a short time heating.
- Only BGA heats directly, and this device does not heat an adjacent part. And PCB bottom heater is unnecessary.
- Positioning of PCB is very simple.
  - ① Do Setting PCB to a work holder.
  - ② Do positioning of BGA to a bottom of a heating tip.
  - ③ Do fixing a work holder with an electromagnet.
- BR-515 is equipped with Thermo-profiler of 3ch. This Thermo-profiler measures heating temperature and time of BGA. Then this Thermo-profiler operates independently.

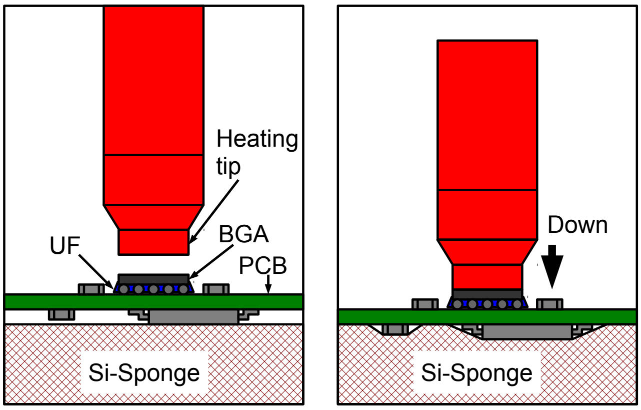
Specifications

- Applicable BGA : 7mm×7mm - 20mm×20mm
- PCB : Normal work holder : 30×30mm - 170×105mm t : 0.4 - 1.2mm
  Optional work holder : 50×50mm - 220×160mm t : 0.4 - 1.6mm
- Heating temperature: Heating bar : 300 - 440°C (Heating tip : 280 - 420°C) PID Control.
- Heating time : Auto : 0.1 - 999.9sec (Timer)
  Manual : START - RESET (Free)
- Heating tip : Aluminum (5052) + Dioxide Molybdenum coating (Hard lubrication coating)
  Normal accessories (3pcs) : 7mm×7mm, 12mm×12mm, 18mm×18mm
  Optional tip : 8mm×8mm, 10mm×10mm, 15mm×15mm,
  20mm×20mm, Special order tip.
- Tip contact pressure : About300g, Pressure adjustment : +5 steps /-2 steps, 0.5mm step.
  Height of a heating tip : +2.5mm (5 steps) / -1.0mm (2 steps)
- Positioning : Take down a heating tip to an around on BGA.
  And match a position with BGA.
- Work holder : Normal work holder : (W)200mm×(D)125mm×(H)21mm 600g
  Optional work holder : (W)240mm×(D)180mm×(H)21mm 1050g
  PCB lower part support : Silicon sponge, attachment t=8mm/10mm
  (consumption articles)
  Positioning : Free (X - Y)
  Fixation : Electromagnetic lock
- Thermo-profiler : 3ch, Software attachment. (PC is not attached.)
- Power supply : Single-phase, AC100V 260W / AC220V 260W
- External dimensions / Weight : (W)260×(D)370×(H)360mm, 13kg

Applications

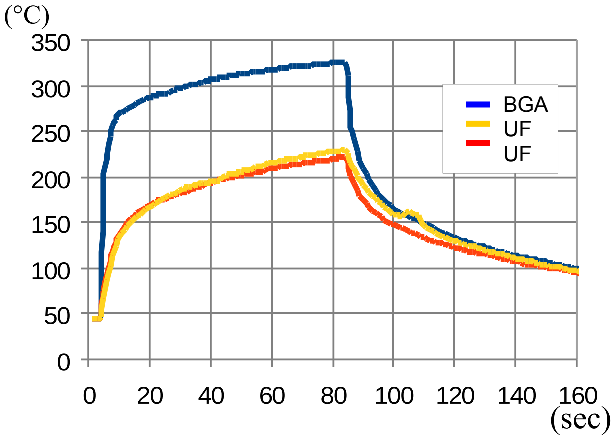
- Work to remove BGA in PCB repair of Smartphone, Automotive navigation system, Tablet PC.
- Removal work of BGA which applied underfill material from PCB.

Heating method



Positioning Heating

Temperature profile



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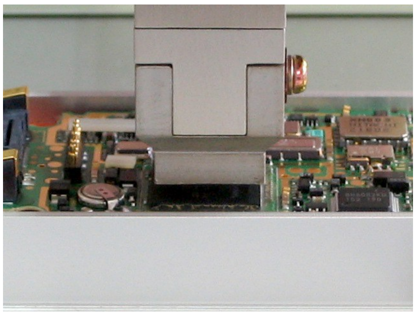
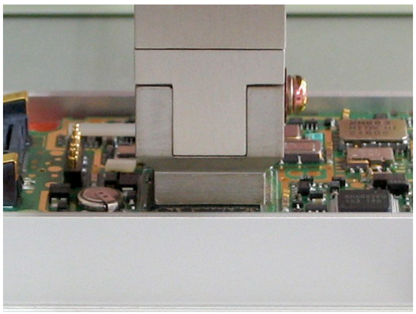
Work procedure

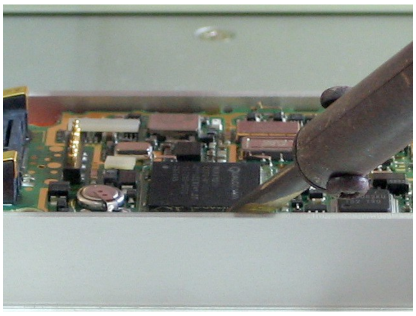
① Set a heating tip of size the same as BGA.
② Set PCB to a work holder.
③ DOWN Take down a heating bar in a positioning level.
④ Move a work holder and match a position of a heating tip with BGA. And LOCK it.

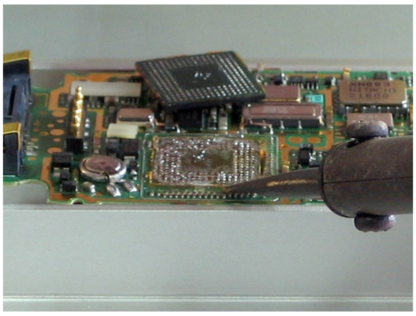


⑤ Set heating temperature (300-440°C) and time (20-80sec).
(Measure a temperature profile and confirm it.)
⑥ AUTO START A heating bar goes down and heats BGA directly from the upper part.



⑦ Then a buzzer sounds, and a heating bar rises time-up. And remove BGA with a spatula (a heating spatula).
MANUAL : A heating bar rises in RESET.





Movie

Look from our Web. http://www.jpl.com/products/smt/asx/BR-515.asx

Main body and Accessories

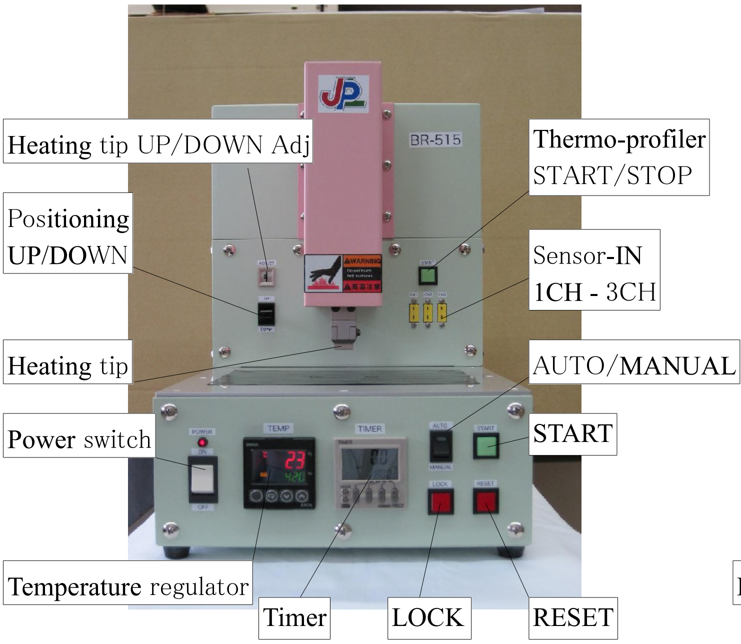
① Main body	1 set
② Heating tip 7mm × 7mm	1 pc
③ Heating tip 12mm × 12mm	1 pc
④ Heating tip 18mm × 18mm	1 pc
⑤ Normal work holder (with sponge)	1 pc
⑥ Sensor K 0.127mmφ	3 pcs
⑦ Kapton tape	1 pc
⑧ USB (RS-232C conversion) cable	1 pc
⑨ Power supply cord	1 pc

Optional parts

- ① Heating tip 8mm × 8mm
- ② Heating tip 10mm × 10mm
- ③ Heating tip 15mm × 15mm
- ④ Heating tip 20mm × 20mm
- ⑤ Heating tip Special order
- ⑥ Optional work holder (with si-sponge)
- ⑦ Si-sponge 130mm × 65mm 8t/10t/12t
- ⑧ Si-sponge 180mm × 120mm 8t/10t/12t

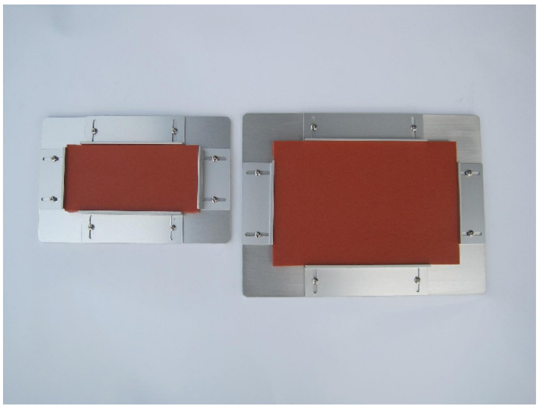
Name of each department

Front



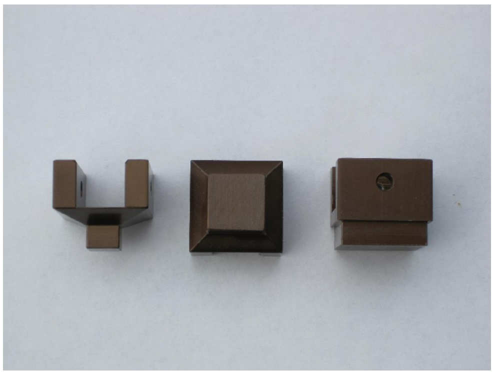
Back side

Work holder



Normal work holder   Optional work holder

Heating tip



7×7mm 12×12mm 18×18mm

*Specifications subject to change without notice.

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